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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/118,080	07/17/1998	WARREN M. FARNWORTH	M4065.067/P0	8629
24998	7590	10/20/2003	EXAMINER	
DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP 2101 L STREET NW WASHINGTON, DC 20037-1526			CHAMBLISS, ALONZO	
			ART UNIT	PAPER NUMBER
			2827	

DATE MAILED: 10/20/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	09/118,080	FARNWORTH, WARREN M.	
	<b>Examiner</b>	<b>Art Unit</b>	
	Alonzo Chambliss	2827	

**-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --**

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 29 September 2003.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1-7 and 10-33 is/are pending in the application.
- 4a) Of the above claim(s) 19-30 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-7, 10-18 and 31-33 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 17 July 1998 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on \_\_\_\_\_ is: a) ☐ approved b) ☐ disapproved by the Examiner.  
If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

**Priority under 35 U.S.C. §§ 119 and 120**

- 13) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
a) ☐ All   b) ☐ Some \*   c) ☐ None of:  
1. ☐ Certified copies of the priority documents have been received.  
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).  
\* See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).  
a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

**Attachment(s)**

- |  |   |
|--|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892)                             | 4) <input type="checkbox"/> Interview Summary (PTO-413) Paper No(s). _____  |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)         | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____ | 6) <input type="checkbox"/> Other: _____                                    |

### **DETAILED ACTION**

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 9/29/03 in Paper No. 23 has been entered.

### ***Response to Arguments***

2. Applicant's arguments filed 9/29/03 have been fully considered but they are not persuasive.

Applicant alleges the combination of Heo and the Master bond reference fail to teach or suggest the claimed feature of " a low temperature curing adhesive material that prevents misalignment between said chip and said single dielectric layer ". This argument is deemed not persuasive because the examiner recognizes that obviousness can only be established by combining or modifying the teachings of the prior art to produce the claimed invention where there is some teaching, suggestion, or motivation to do so found either in the references themselves or in the knowledge generally available to one of ordinary skill in the art. See *In re Fine*, 837 F.2d 1071, 5 USPQ 2d 1596 (Fed. Cir. 1988) and *In re Jones*, 958 F.2d 347, 21 USPQ 2d 1941 (Fed. Cir. 1992). In this case, Heo discloses a semiconductor chip 11, a single dielectric layer, an electrically conductive lead 26 (i.e. conductive circuit pattern) on the dielectric layer 22,

and an adhesive 30 (i.e. epoxy) located between the semiconductor chip and the dielectric layer 21 (see col. 5 lines 18-36, Fig. 4B). With this in mind, the information in the Master Bond Polymer system EP 31 technical data sheet is considered prior since this reference was cited in a P7-0-1449 filed on 81 19/918 and is also as stated on page 8 lines 1-15 of the instant application, the known polymer is marketed as Master Bond Polymer System EP31 by Master Bond Inc., of Hackensack, New Jersey. The technical data sheet discloses an EP31 that is a two-component room temperature (i.e. room temperature) curing epoxy that cures at 75° F at 90% maximum strength developed within 24-36 hours and 1500 F at 90% maximum strength developed within 2-3 hours. The recitation that an element is " sufficient " (i.e. so as to avoid misalignment between said tape and said integrated circuits) to perform a given function is not a positive limitation but only requires the ability to so perform. It does not constitute a limitation in any patentable sense. One skilled in the art would readily recognize that the EP31 composition would avoid misalignment between the tape and integrated circuit, since the EP31 has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding applications that would prevent movement between the tape and the integrated circuit. Heo and the Admitted Prior Art both disclose substantially the same environment of an epoxy as an adhesive in structural bonding applications. Therefore, one skilled in the art would have readily recognized substituting the EP31 epoxy for the epoxy taught by Heo, since the EP31 epoxy has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding

applications and a superb electrical insulator as taught by the Admitted Prior Art (Master Bond Polymer System EP31).

In response to Applicant's argument that the Examiner's conclusion of obviousness is based upon improper hindsight reasoning, it must be recognized that any judgment on obviousness is in a sense necessarily a reconstruction based upon hindsight reasoning. But so long as it takes into account only knowledge which was within the level of ordinary skill at the time the claimed invention was made, and does not include knowledge gleaned only from the applicant's disclosure, such a reconstruction is proper *In re McLaughlin*, 443 F.2d 1392; 170 USPQ 209 (CCPA 1971). One skilled in the art at the time of the invention in light of Heo and the Admitted Prior Art, would have readily recognized substituting the EP31 epoxy for the epoxy taught by Heo, since the EP31 epoxy has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding applications and a superb electrical insulator as taught by the Admitted Prior Art (Master Bond Polymer System EP31).

In response to applicant's argument that there is no suggestion to combine the references, the examiner recognizes that obviousness can only be established by combining or modifying the teachings of the prior art to produce the claimed invention where there is some teaching, suggestion, or motivation to do so found either in the references themselves or in the knowledge generally available to one of ordinary skill in the art. See *In re Fine*, 837 F.2d 1071 , 5 USPQ 2d 1596 (Fed. Cir. 1988) and *In re*

Jones, 958 F.2d 347, 21 USPQ 2d 1941 (Fed. Cir. 1992). In this case, Heo discloses a semiconductor chip 11, a single dielectric layer 21 (i.e. non-conductive film), an electrically conductive leads 26 (i.e. conductive circuit patterns) on the single dielectric layer 21, and adhesive material 30 (i.e. polyimide) located between the single dielectric layer 21 and the semiconductor chip 11 (see col. 5 lines 10-24\*, Figs. 2A, 4B, 513).

Akagawa discloses an anisotropically conductive adhesive material, a polyimide sheet, epoxy sheet used as an insulation film (i.e. non-conductive film) on a circuit pattern 62 (see col. 11 lines 45-57). Thus, the anisotropically conductive adhesive material and polyimide adhesive material behave in the same way in substantially the same environment, since anisotropically conductive adhesive and polyimide adhesive both function as bonding material for a semiconductor device. Furthermore, the anisotropically conductive adhesive functions as an insulating material, which provides an additional source of electrical connection for the semiconductor device. Therefore, one skilled in the art would readily recognize substituting anisotropically conductive adhesive for polyimide material of Heo, since anisotropically conductive adhesive would provide reliable bonding material for a semiconductor device and serve as an additional source of electrical connection for the semiconductor device.

### ***Claim Rejections - 35 USC § 103***

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the

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invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 1, 2, 4-7, 10-14, and 16-18, insofar as being definite, are rejected under 35 U.S.C. 103(a) as being unpatentable over Heo et al. (U.S. 5,858,815) in view of the Admitted Prior Art (Master Bond Polymer System EP31).

With respect to Claim 1, Heo discloses a semiconductor chip 11, a single dielectric layer 20 (i.e. multi-layer film having a non-conductive film layer 21), an electrically conductive lead 26 (i.e. conductive circuit pattern) on the dielectric layer 20, and adhesive 30 (i.e. epoxy) located between the semiconductor chip 11 and the dielectric layer 22 (see col. 5 lines 18-36', Fig. 4B). Heo fails to disclose a low temperature curing adhesive material that cures to about 90% of its maximum strength within 2 to 3 hours without exceeding 1500 F. However, the Admitted Prior Art discloses an EP31 that is a two-component room temperature (i.e. low temperature) curing epoxy that cures at 90% maximum strength developed within 2-3 hours without exceeding 1500 F. Heo and the Admitted Prior Art both disclose substantially the same environment of an epoxy as an adhesive in structural bonding applications. Also, one skilled in the art would readily recognize that the EP31 composition would avoid misalignment between the tape and integrated circuit, since the EP31 has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding applications that would prevent movement between the tape and the integrated circuit. Therefore, one skilled in the art would have readily recognized substituting the EP31 epoxy for the epoxy taught by Heo, since the EP31 epoxy has a high peel strength and good adhesion to a variety of materials

including metals, plastics, rubbers, ceramics, and glass in structural bonding applications and a superb electrical insulator as taught by the Admitted Prior Art (Master Bond Polymer System EP31).

With respect to Claim 2, Heo discloses the dielectric layer 20 (i.e. multi-layer film) including polyimide, since the multi-layer film consist of non-conductive film 21 made of polyimide (see lines 4 col. 45-48 and col. 5 lines 10-17).

With respect to Claim 4, Heo discloses bond wires 40 connecting the semiconductor chip 11 to the electrically conductive leads 26 (see col. 5 lines 50-60', Figs. 2A, 4B, 5B).

With respect to Claim 5, Heo discloses a resin material 50 (i.e. epoxy which is a resin material) encapsulating the bond wires 40 (see col. 6 lines 55-63).

With respect to Claim 6, Heo discloses an opening 23 defined in the dielectric layer 20, wherein bond wires 40 and the resin material 50 are located in the opening (see col. 5 lines 18-24 and col. 6 lines 55-63', Figs. 6B, 7A, 7B, 7C, 8A).

With respect to Claim 7, Heo discloses a ball grid array 60 (i.e. a plurality of solder balls arranged in an array) on the leads 26 (see col. 5 lines 30-36; Fig. 2B).

With respect to Claim 10, Heo discloses integrated circuits formed in a semiconductor material (i.e. semiconductor chip 11), a tape 21, 22 have openings 23 aligned with the integrated circuits that is connected to bond pads 12, wherein the tape 21, 22 includes a single layer 21 and electrically conductive leads 26 (i.e. conductive circuit patterns). The leads 26 are being printed (i.e. patterned) on the single dielectric layer 21. Bond wires 40 extend through the openings, wherein bond wires 40 are



electrically connected to the integrated circuits (see col. 4 lines 35-67 and col. 5 lines 10-17, Fig. 2A, 2B, 4B, 5B). The adhesive material 30 is between the tape 21, 22 and the integrated circuits (see col. 5 lines 18-24; Figs. 2A, 4B, 5B). Heo fails to disclose an adhesive that cures to about 90% of its maximum strength within 24 to 36 hours at room temperature. However, the Admitted Prior Ad discloses an EP31 that is a component room temperature curing epoxy that cures to about 90% of its maximum strength within 24 to 36 hours at room temperature. One skilled in the art would readily recognize that the EP31 composition would avoid misalignment between the tape and integrated circuit, since the EP31 has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding applications that would prevent movement between the tape and the integrated circuit. Heo and the Admitted Prior Ad both disclose substantially the same environment of an epoxy as an adhesive in structural bonding applications. Therefore, one skilled in the art would have readily recognized substituting the EP31 epoxy for the epoxy taught by Heo, since the EP31 epoxy has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding applications and a superb electrical insulator as taught by the Admitted Prior Ad (Master Bond Polymer System EP31).

With respect to Claim 11, Heo discloses a glob top encapsulant 50 (i.e. epoxy which forms a glob of material on top of bond wires 40) in the openings 23 (see col. 5 lines 55-62 and col. 6 lines 55-63\*, Figs. 6B, 7A, 7B, 7C, 8A).

With respect to Claim 12, Heo discloses a ball grid array 60 (i.e. a plurality of

solder balls arranged in an array) for each of the integrated circuits, wherein the ball grid arrays are located on the electrically conductive leads 26 (see col. 5 line 30-36-Fig. 26).

With respect to Claim 13, Heo discloses a single dielectric layer 20 (i.e. multilayer film that includes a non-conductive film 21) having openings 23 with electrically conductive leads 26 (i.e. circuit patterns) associated with the openings 23, wherein the leads are being printed (i.e. patterned) on the dielectric layer 20 (see col. 4 lines 58-67 and col. 5 lines 45-67, Figs. 4B and 5B). The curing adhesive material 30 is located between a semiconductor chip 11 and the dielectric layer 20. Heo fails to disclose a low temperature curing adhesive material that cures to about 90% of its maximum strength within 2 to 3 hours without exceeding 1500 F. However, the Admitted Prior Art discloses an EP31 that is a two-component room temperature (i.e. low temperature) curing epoxy that cures at 90 °C maximum strength developed within 2-3 hours without exceeding 1500 F. One skilled in the art would readily recognize that the EP31 composition would avoid misalignment between the tape and integrated circuit, since the EP31 has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding applications that would prevent movement between the tape and the integrated circuit. Heo and the Admitted Prior Art both disclose substantially the same environment of an epoxy as an adhesive in structural bonding applications. Therefore, one skilled in the art would have readily recognized substituting the EP31 epoxy for the epoxy taught by Heo, since the EP31 epoxy has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding

applications and a superb electrical insulator as taught by the Admitted Prior Art (Master Bond Polymer System EP31).

With respect to Claim 14, Heo discloses the dielectric layer 20 (i.e. multi-layer film) includes polyimide, since the multi-layer film consist of non-conductive film made of polyimide (see lines 4 col. 45-48 and col. 5 lines 10-17).

With respect to Claim 16, Heo discloses the dielectric layer 20 (i.e. multi-layer film) includes a metal alloy (i.e. circuit pattern 26 made of a copper foil) and a nonconductive film 21 made of polyimide (see col. 5 lines 10-17).

With respect to Claim 17, Heo discloses openings 23 that are slot-shaped to expose aligned bond pad 12 (see col. Figs. 4A, 4B, 5A, 5B).

With respect to Claim 18, Heo discloses openings 23 in the dielectric layer 20 (see col. 5 lines 48-55;Figs. 4B, 5B). The punched through feature in the claim is inherent in the reference, since any perforation in the dielectric layer 21 is equivalent to drilling or punching.

5. Claims 3 and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Heo et al. (U.S. 5,858,815) and the Admitted Prior Art (Master Bond Polymer System EP31 ) as applied to claims 1 and 13 above, and further in view of Chang et al, (U.S. 5,559,055).

With respect to Claims 3 and 15, Heo discloses a dielectric layer 20 (i.e. multilayer film) including a non-conductive film 21 made of polyimide (see col. 5 lines 18-22). Heo-Admitted Prior Ad both fail discloses a dielectric layer (i.e. insulating film) including a benzocyclobutene. However, Chang discloses a dielectric layer including a

benzocyclobutene having the same dielectric constant as polyimide. Also, benzocyclobutene is selected from the same group of dielectric materials as polyimide (see col. 4 lines 55-67, col. 6 lines 66 and 67, and col. 7 lines 1-3). Thus, benzocyclobutene and polyimide behave in the same way in substantially the same environment, since benzocyclobutene and polyimide are both low K dielectric materials, which provide protection for metal circuit patterns in semiconductor devices. Therefore, one skilled in the art would have readily recognize that benzocyclobutene and polyimide are interchangeable, since benzocyclobutene and polyimide are both low K dielectric material that provide protection for metal circuit patterns in semiconductor devices as taught by Chang.

6. Claims 31-33 are rejected under 35 U.S.C. 103(a) as being unpatentable over Heo et al. (U.S. 5,858,815) in view of Akagawa (U.S. 6,121,688).

With respect to Claim 31, Heo discloses a semiconductor chip 11, a single dielectric layer 21 (i.e. non-conductive film), an electrically conductive leads 26 (i.e. conductive circuit patterns) on the single dielectric layer 21, and adhesive material 30 (i.e. polyimide) located between the single dielectric layer 21 and the semiconductor chip 11 (see col. 5 lines 10-24\*, Figs. 2A, 4B, 513). Heo fails to explicitly disclose an anisotropically conductive adhesive material. However, Akagawa discloses an anisotropically conductive adhesive material, a polyimide sheet, epoxy sheet used as an insulation film (i.e. non-conductive film) on a circuit pattern 62 (see col. 11 lines 45-57). Thus, the anisotropically conductive adhesive material and polyimide adhesive material behave in the same way in substantially the same environment, since anisotropically

conductive adhesive and polyimide adhesive both function as bonding material for a semiconductor device. Furthermore, the anisotropically conductive adhesive functions as an insulating material, which provides an additional source of electrical connection for the semiconductor device. Also, one skilled in the art would readily recognize that the EP31 composition would avoid misalignment between the tape and integrated circuit, since the EP31 has a high peel strength and good adhesion to a variety of materials including metals, plastics, rubbers, ceramics, and glass in structural bonding applications that would prevent movement between the tape and the integrated circuit. Therefore, one skilled in the art would readily recognize substituting anisotropically conductive adhesive for polyimide material of Heo, since anisotropically conductive adhesive would provide reliable bonding material for a semiconductor device and serve as an additional source of electrical connection for the semiconductor device.

With respect to Claim 32, Heo discloses via holes 23 (i.e. openings) defined in the single dielectric layer 21 and metal 40 (i.e. metal bond wires that provide electrical signals to the leads 26) located in the via holes 23, wherein the metal 40 is connected to the leads 26 (see col. 5 lines 10-36, Figs. 4A, 4B, and 5B).

With respect to Claim 33, Heo discloses a ball grid array 60 (i.e. a plurality of solder balls arranged in an array) on the leads 26, wherein the ball grid array 60 is located within the periphery of the chip 11 (see col. 5 line 30-36; Figs. 2B, 7B, 7C).

The prior art made of record and not relied upon is cited primarily to show the process of the instant invention.

**Conclusion**

7. Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonzo Chambliss whose telephone number is (703) 306-9143. The fax phone number for this Group is (703) 308-7722 or 7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-7956

**AC/October 14, 2003**

A handwritten signature in black ink, appearing to read "Alonzo Chambliss". The signature is written in a cursive, flowing style.

Alonzo Chambliss  
Patent Examiner  
Art Unit 2827